

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YU-CHEN MA	04/09/2021
HSIN-HAO HUANG	04/09/2021
WEN-FU CHOU	04/09/2021
GWO-SHYAN SHEU	04/09/2021
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<b>Name:</b>	CHIPBOND TECHNOLOGY CORPORATION
<b>Street Address:</b>	No.3, Lihsin 5 Rd., Hsinchu Science Park
<b>City:</b>	Hsinchu
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17227470
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	7017.339
<b>NAME OF SUBMITTER:</b>	DEMIAN K. JACKSON
<b>SIGNATURE:</b>	/Demian K. Jackson/
<b>DATE SIGNED:</b>	04/12/2021
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 2</b>	
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**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN  
APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE**

**Title of  
Invention**

LAYOUT STRUCTURE OF A FLEXIBLE CIRCUIT BOARD

As the below named inventor, I hereby declare that:

This declaration  The attached application, or

is directed to:  United States application or PCT international application number \_\_\_\_\_  
filed on \_\_\_\_\_.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

WHEREAS,

CHIPBOND TECHNOLOGY CORPORATION

(hereinafter referred to as "ASSIGNEE") having places of business at: No. 3, Lihsin 5 Rd., Hsinchu Science Park, Hsinchu, Taiwan, R.O.C.

is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt whereof is hereby acknowledged, I, by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries (including the right to claim priority under the terms of the International Convention and other relevant International Treaties and Arrangements from the aforesaid application) and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.

I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me had this Assignment and sale not been made.

Further, I agree that I will communicate to said ASSIGNEE or its (his) representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment(s) referred to above. I acknowledge the Duty to Disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

LEGAL NAME OF INVENTOR

Inventor: Yu-Chen Ma

Date: April 9, 2021

Signature: /Yu-Chen Ma/

**JACKSON INTELLECTUAL PROPERTY  
GROUP PLLC  
106 STARVALE LANE  
SHIPMAN, VA 22971**

CONTINUATION OF DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Page 2

Full Name of Joint Inventor Hsin-Hao Huang Date April 9, 2021  
Signature /Hsin-Hao Huang/

Full Name of Joint Inventor Wen-Fu Chou Date April 9, 2021  
Signature /Wen-Fu Chou/

Full Name of Joint Inventor Gwo-Shyan Sheu Date April 9, 2021  
Signature /Gwo-Shyan Sheu/

Full Name of Joint Inventor \_\_\_\_\_ Date \_\_\_\_\_  
Signature \_\_\_\_\_

Full Name of Joint Inventor \_\_\_\_\_ Date \_\_\_\_\_  
Signature \_\_\_\_\_

Full Name of Joint Inventor \_\_\_\_\_ Date \_\_\_\_\_  
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See following pages for additional joint inventors

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